

* 0850 Series Mini Universal Serial Bus Connector *

This product specification contains the test method, the general performance and requirements for 0850 Series Mini Universal serial bus connector.

1. Construction and dimensions shall be in accordance with the referenced drawings.

(产品结构 and 尺寸依据所提供的产品图面)

2. Characteristics (特性) :

Current rating (额定电流) : 1.0A AC/DC

Voltage rating (额定电压) : 30V ac(rms)

Temperature rating (额定温度) : -20°C ~ +85°C

3. Electrical performance (电气特性) :

Item	Description (内容)	Test Method & Condition (测试方法与条件)	Requirement(需求)
3-1	Contact Resistance (接触阻抗)	EIA 364-23 Subject mates contacts assembled in housing, to 20mv Maximum open circuit at 100mA maximum	50mΩ maximum
3-2	Insulation Resistance (绝缘阻抗)	EIA 364-21 Test between adjacent contacts of mated and unmated connector assemblies.	100MΩ minimum
3-3	Dielectric Withstanding Voltage (耐电压)	EIA 364-20 Test between adjacent contacts of mated and unmated connector assemblies.	100Vac at sea level

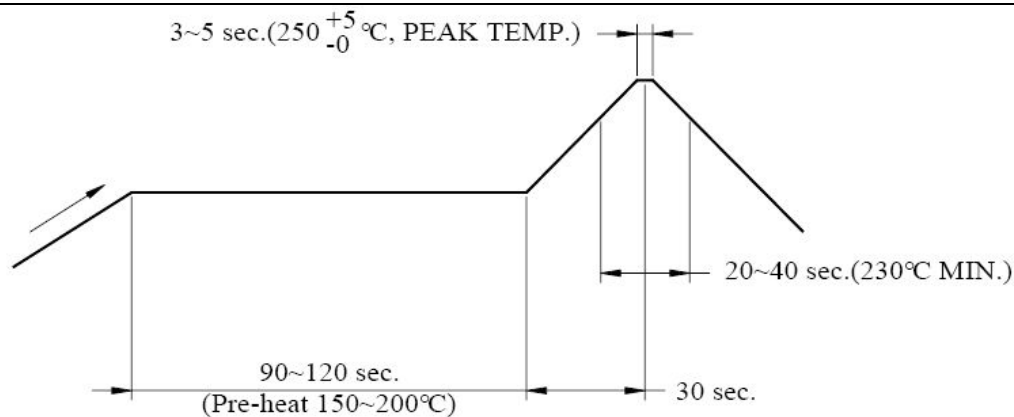
4. Mechanical Performance(机械特性) :

Item	Description(内容)	Test Method & Condition (测试方法与条件)	Requirement(需求)
4-1	Mating Force (插入力)	EIA 364-13 Measure force necessary to mated connector assemblies at maximum rate of 12.5 mm per minute.	3.57 kgf (35N)maximum
4-2	Unmating Force (拔出力)	EIA 364-13 Measure force necessary to unmated connector assemblies at maximum rate of 12.5 mm per minute	0.71 kgf (7N)minimum
4-3	Durability (耐久性)	EIA 364-09 Mate and unmate connector assemblies for 5000 cycle at maximum rate of 200 cycle per hour.	Appearance:No Breakdown Contact Resistance:50 mΩ Maximum

5. Environmental Performance (环境特性) :

Item	Description (内容)	Test Method & Condition(测试方法与条件)	Requirement(需求)
5-1	Humidity (耐湿性)	EIA 364-31 Method III test condition A. Subject mated connectors to 96 hours at 40°C with 90 to 95% RH.	No evidence of damage. Contact resistance less Than twice of initial. Insulation resistance: to pass para. 3-2 Dielectric withstanding voltage: to pass para 3-3
5-2	Solderability (着锡性)	.Soldering time :5±0.5 second Soldering pot:245±5 °C	No damage and deformation Minimum:95% of immersed area
5-3	Resistance to soldering Heat (耐焊锡热)	Soldering time:5±0.5 second Soldering pot:260±5°C When reflowing: 2 cycles	No damage and deformation
5-4	Salt spray 盐雾测试	Temperature:35±3°C Solution:5±1% Spray time:12 hours Measurement must be taken after water rinse	No damage Contact resistance: Less than twice of initial

6. Infrared Reflow Condition:



TEMPERATURE CONDITION GRAPH
(TEMPERATURE ON BOARD PATTERN SIDE)

NOTE: Please check the mount condition(reflow soldering condition) by your own devices beforehand, because the condition changes by the soldering devices, p.c.boards, and so on. No moisture treatment before reflow process.

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